

PCN Number:	20250319003.1		PCN Date:	June 04, 2025	
Title:	Qualification of DFAB as an additional Fab site option for select JIBB devices				
Customer Contact:	Change Management Team		Dept:	Quality Services	
Proposed 1st Ship Date:	September 02, 2025		Sample requests accepted until:	August 03, 2025*	
*Sample requests received after August 03, 2025 will not be supported.					
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Wafer Fab Material
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
Texas Instruments is pleased to announce the addition of DFAB as an additional Wafer Fab option for the devices listed below.					
Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
SFAB	JIBB	150 mm	DFAB	JIBB	200 mm
Qual details are provided in the Qual Data Section.					
Reason for Change:					
These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Changes to product identification resulting from this PCN:					
Fab Site Information:					
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City		
SH-BIP-1	SHE	USA	Sherman		
DL-LIN	DLN	USA	Dallas		
Sample product shipping label (not actual product label):					
Product Affected:					

DRV134PA	INA134UA	INA2137UA/2K5	OPA544F/500
DRV134PA.A	INA134UA.A	INA2137UA/2K5.A	OPA544F/500.A
DRV134UA	INA134UA/2K5	INA2141U	OPA544FKTTT
DRV134UA.A	INA134UA/2K5.A	INA2141U.A	OPA544FKTTT.A
DRV134UA/1K	INA137UA	INA2141UA	OPA544T
DRV134UA/1K.A	INA137UA.A	INA2141UA.A	OPA544T.A
DRV135UA	INA137UA/2K5	INA2141UA/1K	OPA548F/500
DRV135UA.A	INA137UA/2K5.A	INA2141UA/1K.A	OPA548F/500.A
DRV135UA/2K5	INA138NA/250	ISO122JP	OPA548FKTWT
DRV135UA/2K5.A	INA138NA/250.A	ISO122JP.A	OPA548FKTWT.A
INA103KP	INA138NA/3K	ISO122JP.B	OPA548T
INA103KP.A	INA138NA/3K.A	ISO122JPE4	OPA548T.A
INA103KU	INA139NA/250	ISO122JU	OPA548T-1
INA103KU.A	INA139NA/250.A	ISO122JU.A	OPA548T-1.A
INA103KU/1K	INA139NA/3K	ISO122JU.B	OPA551FA/500
INA103KU/1K.A	INA139NA/3K.A	ISO122JU/1K	OPA551FA/500.A
INA111AP	INA154U	ISO122JU/1K.A	OPA551FA/500G3
INA111AP.A	INA154U.A	ISO122JU/1K.B	OPA551FAKTWT
INA111AU	INA154U/2K5	ISO122JUE4	OPA551FAKTWT.A
INA111AU.A	INA154U/2K5.A	ISO122P	OPA551FAKTWTG3
INA111AU/1K	INA154UA	ISO122P.A	OPA551PA
INA111AU/1K.A	INA154UA.A	ISO122P.B	OPA551PA.A
INA111BP	INA157U	ISO122PE4	OPA551UA
INA111BP.A	INA157U.A	ISO122U	OPA551UA.A
INA111BU	INA157U/2K5	ISO122U.A	OPA551UA/2K5
INA111BU.A	INA157U/2K5.A	ISO122U.B	OPA551UA/2K5.A
INA121P	INA157UA	ISO122U/1K	REF02AU
INA121P.A	INA157UA.A	ISO122U/1K.A	REF02AU.A
INA121PA	INA157UA/2K5	ISO122U/1K.B	REF02AU/2K5
INA121PA.A	INA157UA/2K5.A	ISO122UE4	REF02AU/2K5.A
INA121U	INA168NA/250	ISO124P	REF02BU
INA121U.A	INA168NA/250.A	ISO124P.A	REF02BU.A
INA121U/2K5	INA168NA/3K	ISO124P.B	REF02BU/2K5
INA121U/2K5.A	INA168NA/3K.A	ISO124U	REF02BU/2K5.A
INA121UA	INA169NA/250	ISO124U.A	REF102AU
INA121UA.A	INA169NA/250.A	ISO124U.B	REF102AU.A
INA121UA/2K5	INA169NA/3K	ISO124U/1K	REF102AU/2K5
INA121UA/2K5.A	INA169NA/3K.A	ISO124U/1K.A	REF102AU/2K5.A
INA128HD	INA2134UA	ISO124U/1K.B	REF102BU
INA128HD.A	INA2134UA.A	ISO124U/1KE4	REF102BU.A
INA128P	INA2134UA/2K5	ISO124UE4	REF102CU
INA128P.A	INA2134UA/2K5.A	OPA2604AU	REF102CU.A
INA128PA	INA2134UA/2K5G4	OPA2604AU.A	REF102CU/2K5
INA128PA.A	INA2137UA	OPA2604AU/2K5	REF102CU/2K5.A
INA128PG4	INA2137UA.A	OPA2604AU/2K5.A	

For alternate parts with similar or improved performance, please visit the product page on [TI.com](https://www.ti.com)

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: INA168QDBVRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0
HTSL	A6	High Temperature Storage Life	175C	500 Hours	1/45/0
HTOL	B1	Life Test	125C	1000 Hours	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	3/2400/0
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	1/15/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	3/30/0
ESD	E2	ESD CDM	-	1000 Volts	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/6/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	3/90/0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device INA168QDBVRQ1 is qualified at MSL1 260C
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- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2206-002

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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